12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250916000.1
Qualify New Assembly Material set for Selected Device(s)
Change Notification / Sample Request

Date: September 17, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250916000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS7844EBG4	ADS7844EB
ADS7841ES	ADS7841ES
ADS7844EB	ADS7844EB
ADS7841EB	ADS7841EB

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250916000.1	**PCN Date:**	September 17, 2025
Title:	Qualify New Assembly Material set for Selected Device(s)		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	December 16, 2025	**Sample requests accepted until:**	November 16, 2025

***Sample requests received after** November 16, 2025 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

	Current	Proposed
Mount compound	4042500	4147858
Mold compound	4206193, 4209002	4211471

Reason for Change:

Continuity of supply.
Current mount compound production support until December 2025.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

74AVC16245DGGR-P	ADS7841EB	ADS7844EBG4	TLC8424FIDBTR-P
74LVCH16244AGR-P	ADS7841ES	AVCH16T245DGGR-P	
74LVCH16245AGR-P	ADS7844EB	TLC8224FIDBTR-P	

Qualification Report

Approve Date 14-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN1301037NSR	Qual Device: TLC5949DBQR	Qual Device: SN74CBTLV16800VR	Qual Device: MSP430F1121AIDGVR
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	1/22/0	1/22/0	-
FTY	E6	Final Test Yield	-	-	3/3/0	3/3/0	3/3/0	3/3/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN1301037NSR is qualified at MSL1 260C
Qual Device TLC5949DBQR is qualified at MSL2 260C
Qual Device SN74CBTLV16800VR is qualified at MSL1 260C
Qual Device MSP430F1121AIDGVR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-086

Qualification Report

Approve Date 26-Aug-2016

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: 8BT245MDGGEP	Qual Device: 8X512DGGR	Qual Device: ADS1259BIPWR	Qual Device: CLVC374APWR	Qual Device: E8722DGGR	Qual Device: SN200708045DAR	Qual Device: SN65MLVD129DGG
AC	Autoclave 121C	96 Hours	3/231/0	-	-	-	3/231/0	3/231/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	Pass	-	-	-
HAST	Biased HAST, 130C/85%RH	192 Hours	-	-	-	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0	-	-	-	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass	Pass	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0
VM	Visual Quality Reliability Inspection	Post Autoclave 96 Hours	-	-	-	-	-	3/6/0	-
VM	Visual Quality Reliability Inspection	Post Biased HAST 96 Hours	-	-	-	-	-	-	-
VM	Visual Quality Reliability Inspection	Post Temp Cycle 500 Cycles	-	3/6/0	-	-	-	3/6/0	-

Type	Test Name / Condition	Duration	Qual Device: THS4524IDBTR	Qual Device: TPS2111PWR	Qual Device: TPS23861PWR	Qual Device: TPS43000PW	QBS Package Reference: SN65C1168PWR	QBS Package Reference: TAS5086DBT	QBS Package Reference: TPIC1353DBTRG4
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	-	-	3/231/0	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	-
HAST	Biased HAST, 130C/85%RH	192 Hours	-	-	3/231/0	-	3/227/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	3/227/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	3/231/0	3/231/0	3/231/0	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass	Pass	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	-	3/231/0	3/230/0	3/231/0	3/231/0
VM	Visual Quality Reliability Inspection	Post Autoclave 96 Hours	3/6/0	3/6/0	-	-	-	-	-
VM	Visual Quality Reliability Inspection	Post Biased HAST 96 hours	-	-	3/6/0	-	-	-	-
VM	Visual Quality Reliability Inspection	Post Temp Cycle 500 Cycles	3/6/0	3/6/0	-	3/6/1(1)	-	-	-

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260CG: E8722DGGR, TPS43000PW, SN200708045DAR , CLVC374APWR, TPS2111PWR, 8X512DGGR, 8BT245MDGGEP, ADS1259BIPWR
- Qual Devices qualified at LEVEL2-260CG: SN65MLVD129DGG, THS4524IDBTR, TPS23861PWR
- Device THS4524IDBTR contains multiple dies.
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

(1) Note: 1 unit in VQR Post Temp Cycle 500 Cycles showed a high amount of lead delamination with a cracked stitch. Extended readpoint units did not show this, and post T/C wirepull passed. SC Packaging has provided these corrective actions: 1) Long term continuous improvement of using pro-stitch for 2nd bond, 2) SuHD rough leadframes for better adhesion of mold and die attach to leadframe.
TI Qualification ID: 20141216-110350
QBS Qualification ID: 20101012-26302

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.